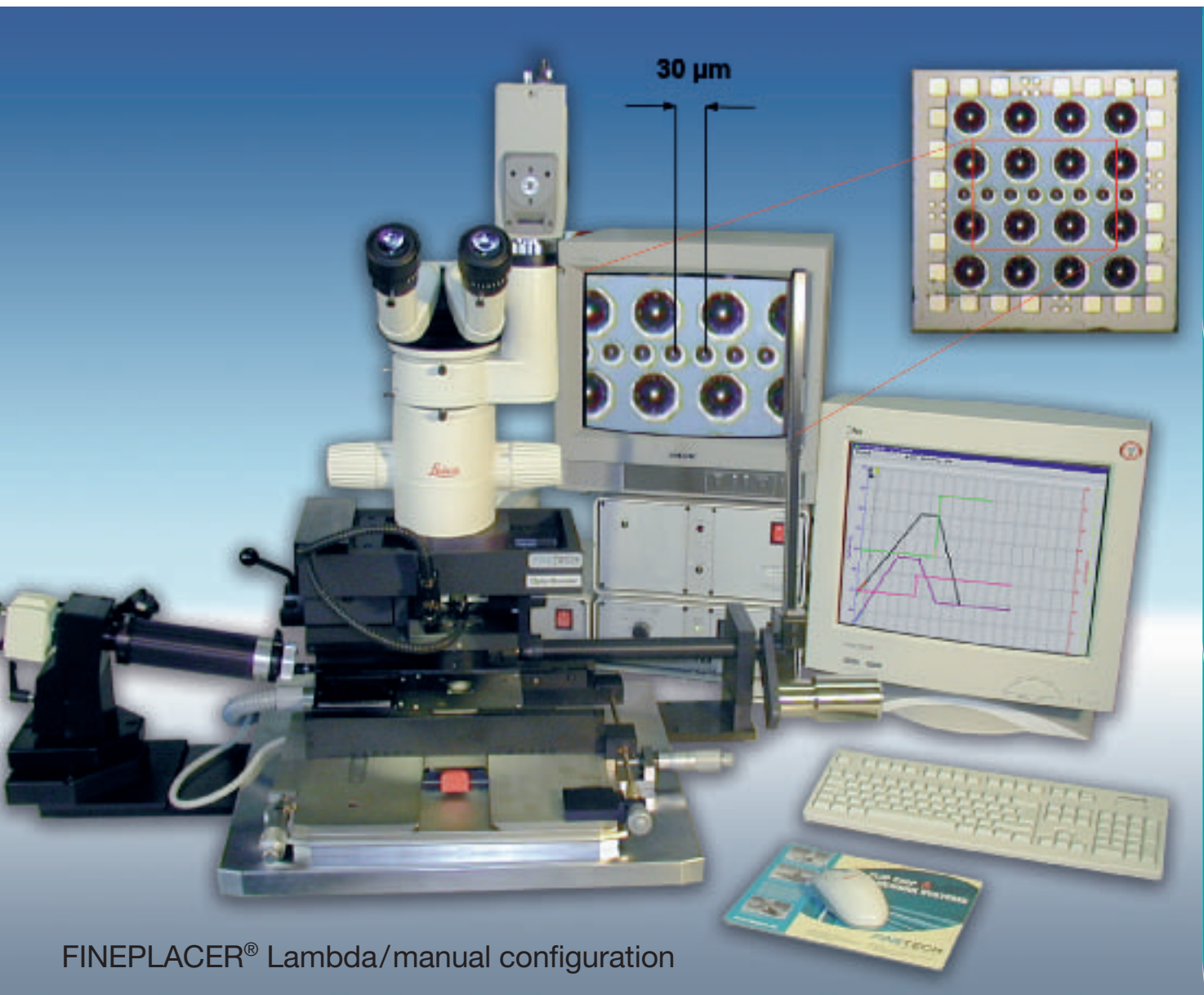


FINEPLACER® Lambda

The ONE MICRON Machine



FINEPLACER® Lambda/manual configuration

PRECISE PLACEMENT

ASSEMBLY

BONDING

ONE MICRON placement accuracy

- Patented Vision Alignment System with fixed optical beam splitter
- The simplest, easy-to-learn bonding platform
- Modular design and flexible upgrade capability
- Compact design with minimal moving parts
- Die size from 100 micron to 35 mm
- Die Placement face-up or face-down
- Controlled force to 40 kg
- Temperatures to 400°C
- Ready for sophisticated future technologies

Multi-Application Capabilities

Precise Die Attach

Flip Chip Bonding

- Thermo Compression
- Ultra Sonic
- Eutectic C4
- Chip On Glass (ACF)

Assembly of Opto-electronic components

- Active and passive fiber alignment

Assembly of MEMS, MOEMS, sensors and micro-optics

ACF Repair

Microassembly

- Dispensing
- UV Cure

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FINETECH
...simply accurate

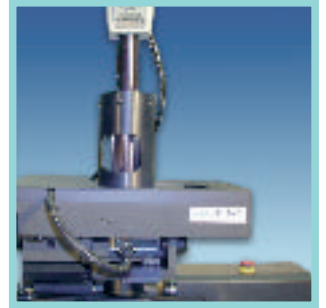
FINEPLACER® Lambda

Automated Operation

Equipped with the automatic module package consisting of the Automatic Bonding Force Module, Motorized Microscope Movement and PC Control and Bonding WIN Flip Chip Software. The new FINEPLACER® Lambda provides auto-touchdown and die placement as well as controlled bonding operation after manual alignment of die and substrate.

Advantages:

- Hands-off die placement
- Improved process repeatability – pilot production worthy
- Places die whose dimensions exceed the optical field of view
- Up to 10 programmable microscope positions
- Upgradeable with integrated microscope measurement function and a placement mask generator



Motorized Microscope Movement with mono ocular microscope

Technical Data

Placement accuracy	Lambda A6 1 micron Lambda A7 sub 1 micron
Chip sizes	From 100 micron to 35 mm
Substrate sizes	Max. 180x108 mm
Automatic Upgrade of Base System Automatic Bonding Force Module Motorized Microscope Movement	Force range 1N – 100N, resolution 1N Movement range 40 mm, Speed 40 mm/s Resolution 0,1 micron, accuracy 0,5 micron PC Control and Bonding WIN Flip Chip Software
Process control	



Automatic Bonding Force Module



Automatic FINEPLACER® Lambda

NEW

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